



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A1406-01	DATE: 7-Apr-2015	MEANS OF DISTINGUISHING CHANGED DEVICES: ☐ Product Mark ☒ Back Mark ☐ Date Code ☐ Other
Product Affected: VFQFPN-28, VFQFPN-32, VFQFPN-36 Refer to Attachment II for the affected part numbers		
Date Effective: 7-Jul-2015		Lot # will have: "P" prefix for Amkor, Philippines "RC" prefix for ASECL, Taiwan

Contact: IDT PCN DESK	Attachment: ☒ Yes ☐ No
E-mail: pcndesk@idt.com	Samples: Please contact your local sales representative for sample request.

DESCRIPTION AND PURPOSE OF CHANGE:

☐ Die Technology	This notification is to advise our customers that IDT is adding Amkor, Philippines (ATP) and ASE Chungli, Taiwan (ASECL) as alternate Assembly facilities.
☐ Wafer Fabrication Process	
☐ Assembly Process	There is no change to the moisture performance.
☐ Equipment	
☐ Material	Attachment I details the qualification data for this change and Attachment II shows the affected list of part numbers.
☐ Testing	
☒ Manufacturing Site	
☐ Data Sheet	
☐ Other	

RELIABILITY/QUALIFICATION SUMMARY:

Refer to qualification data shown in Attachment I.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	☐ Approval for shipments prior to effective date.
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:	
RECD. BY: _____	DATE: _____



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ATTACHMENT I - PCN # : A1406-01

PCN Type: Manufacturing Site - Alternate Assembly Locations

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT is adding Amkor, Philippines (ATP) and ASE Chungli (ASECL) as alternate Assembly facilities. Presently, ATP and ASECL are qualified IDT Subcontractor.

The material set details of the current and alternate assembly locations is as shown in Table 2. The die attach and mold compound used at the alternate assembly are qualified IDT materials. There is no change from the existing qualified lead frame material, lead finish, and wire for the alternate assembly locations.

There is no change to the moisture performance.

Table 1: The Existing and Alternate Assembly Locations

	Existing Assembly	Alternate Assembly	
Package	ATK - Amkor, Korea	ATP - Amkor, Philippines	ASECL - ASECL, Taiwan
VFQFPN-28 VFQFPN-32 VFQFPN-36	X	X	X

Note: X denote qualified assembly location

Table 2: Assembly Material Sets for The Existing and Alternate Assembly Locations

	Existing Assembly	Alternate Assembly	
Material Set / Assembly	ATK - Amkor, Korea	ATP - Amkor, Philippines	ASECL - ASECL, Taiwan
Die Attach	CRM1085A	CRM1085A	EN4900G
Wire	PdCu wire	PdCu wire	PdCu wire
Mold Compound	G700, G631BQF	G700, G631BQF	G700LA



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ATTACHMENT I - PCN # : A1406-01

Qualification Information and Qualification Data:

Affected Packages: VFQFPN-28, VFQFPN-32, VFQFPN-36

Assembly Material: The affected package type is using ATP and ASECL standard materials shown on page 2 of this attachment.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Qualification Vehicle: VFQFPN-36 (4 lots)

Test Description	Test Method	Test Results (Rej / SS)
* HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0/30, 0/30, 0/30, 0/30
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/30, 0/30, 0/30, 0/30
High Temperature Storage Test (150°C, 1000 hours)	JESD22-A103	0/30, 0/30, 0/30, 0/30

* Tests were subjected to Preconditioning per JESD22-A113 prior to stress test



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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT II - PCN # : A1406-01

Affected Part Numbers

Part Number	Part Number	Part Number	Part Number
F1100NBGI	F1150NBGI8	F1200NBGI	F1241NBGI8
F1100NBGI8	F1152NBGI	F1200NBGI8	F1350NBGI
F1102NBGI	F1152NBGI8	F1240NBGI	F1350NBGI8
F1102NBGI8	F1162NBGI	F1240NBGI8	F1370NBGI
F1150NBGI	F1162NBGI8	F1241NBGI	F1370NBGI8